

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60V	8.5mΩ@10V	80A

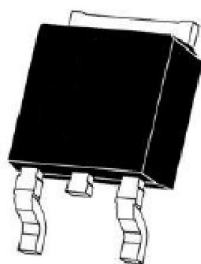
Feature

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation
- Suffix "-Q1" for AEC-Q101

Application

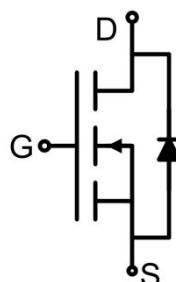
- Load Switching
- PWM

Package



TO-252AB

Circuit diagram



Marking



Absolute maximum ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	80	A
Continuous Drain Current(T _C =100 °C)	I _D (100 °C)	56.5	A
Pulsed Drain Current	I _{DM}	320	A
Power Dissipation	P _D	110	W
Thermal Resistance,Junction-to-Ambient	R _{θJA}	60	°C/W
Thermal Resistance,Junction-to-Case	R _{θJC}	1.36	°C/W
Single pulse avalanche energy	E _{AS}	390	mJ
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_C=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	2.8	4.0	V
Drain-source on-resistance ¹⁾	R _{DS(on)}	V _{GS} =10V, I _D =20A		7	8.5	mΩ
Dynamic characteristics²⁾						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f =1MHz		4000		pF
Output Capacitance	C _{oss}			290		
Reverse Transfer Capacitance	C _{rss}			210		
Total Gate Charge	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =20A		90		nC
Gate-Source Charge	Q _{gs}			9		
Gate-Drain Charge	Q _{gd}			18		
Turn-on delay time	t _{d(on)}	V _{DD} =30V, V _{GS} =10V, R _L =1Ω, R _{GEN} =3Ω		8.5		nS
Turn-on rise time	t _r			7		
Turn-off delay time	t _{d(off)}			40		
Turn-off fall time	t _f			15		
Source-Drain Diode characteristics						
Diode Forward Current ¹⁾	I _S				80	A
Diode Forward voltage	V _{DS}	V _{GS} =0V, I _S =20A			1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =20A		32		nS
Reverse Recovery Charge	Q _{rr}	di/dt = 500A/μs ¹⁾		45		nC

Notes:

1) Pulse Test: Pulse Width < 300μs, Duty Cycle ≤2%.

2) Guaranteed by design, not subject to production testing.

Typical Characteristics

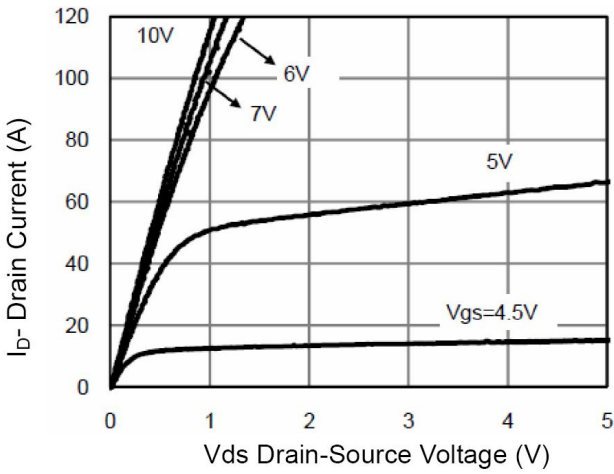


Figure 1 Output Characteristics

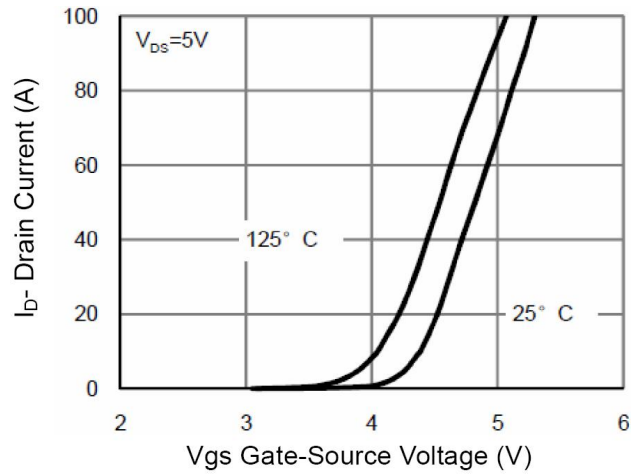


Figure 2 Transfer Characteristics

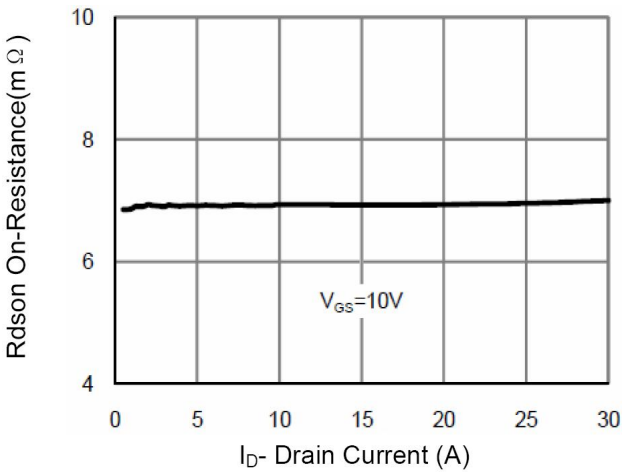


Figure 3 Rdson- Drain Current

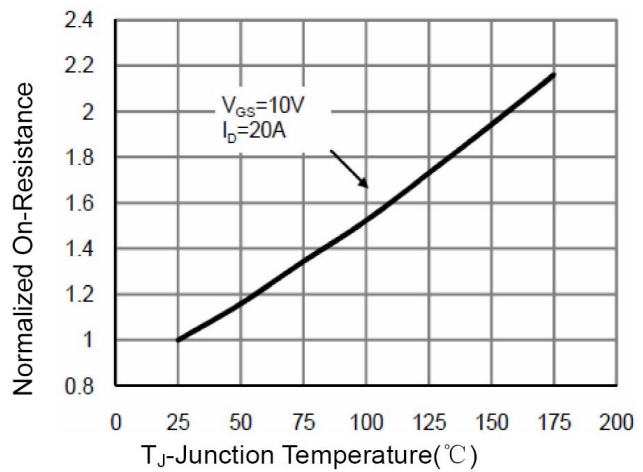


Figure 4 Rdson-Junction Temperature

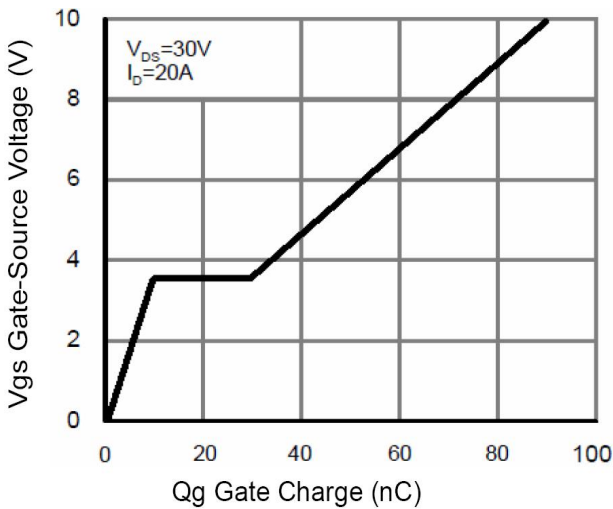


Figure 5 Gate Charge

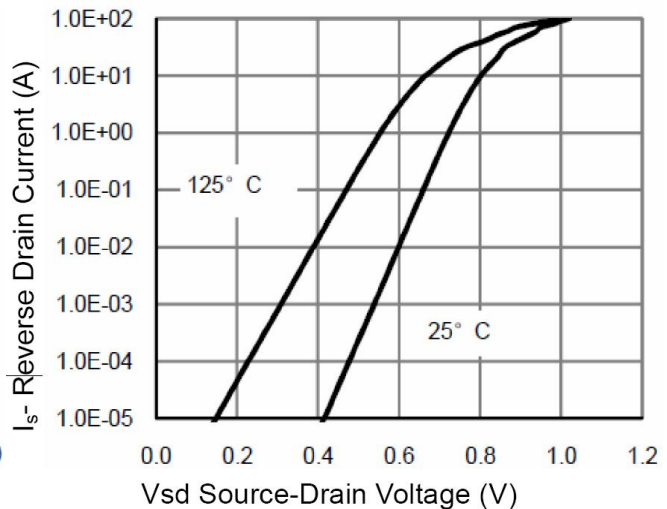


Figure 6 Source- Drain Diode Forward

Typical Characteristics

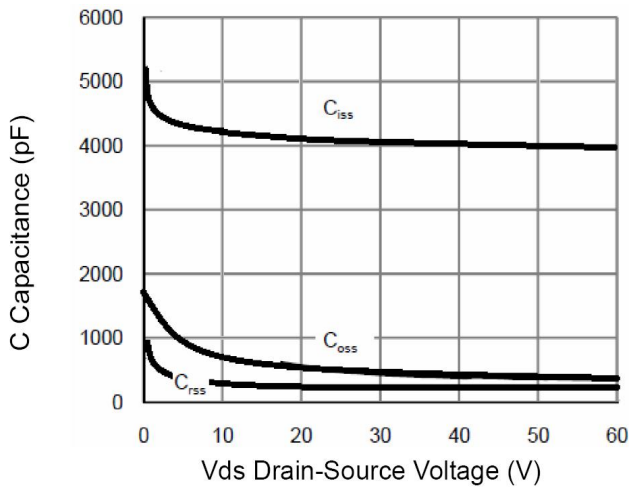


Figure 7 Capacitance vs Vds

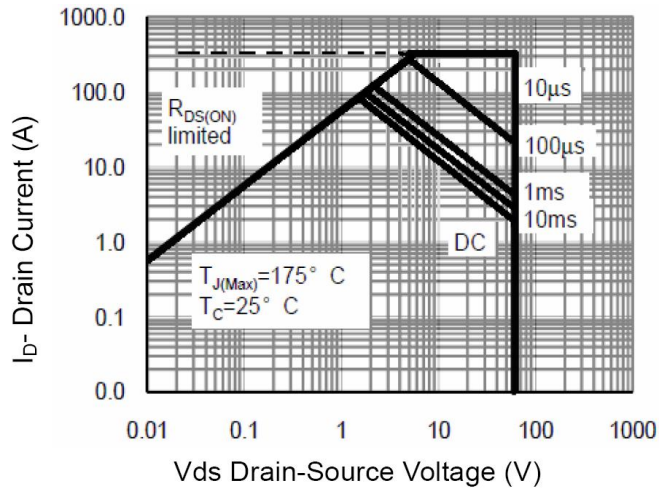


Figure 8 Safe Operation Area

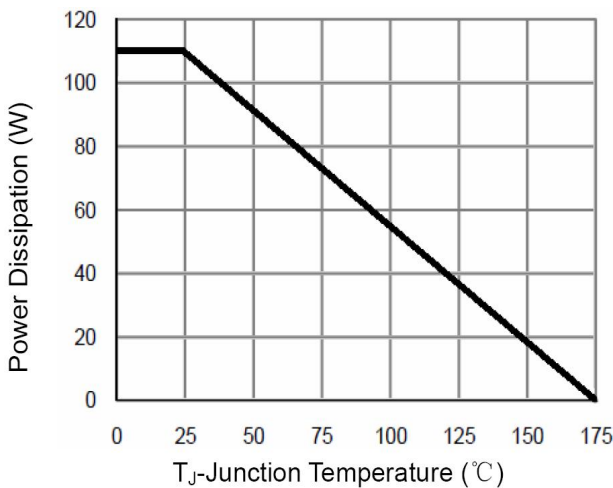


Figure 9 Power De-rating

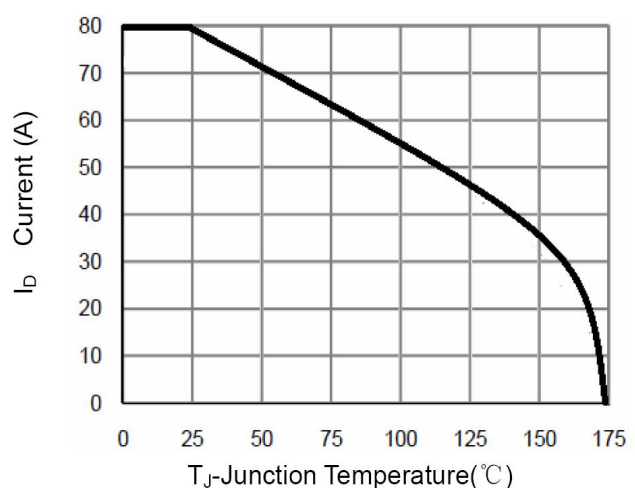


Figure 10 Id Current- Junction Temperature

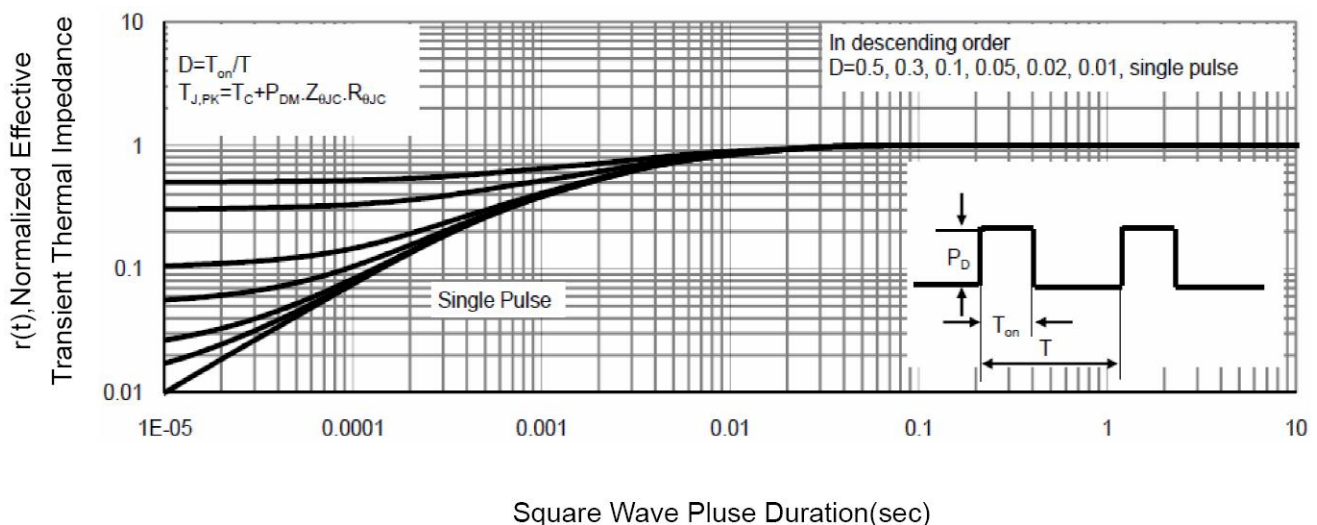
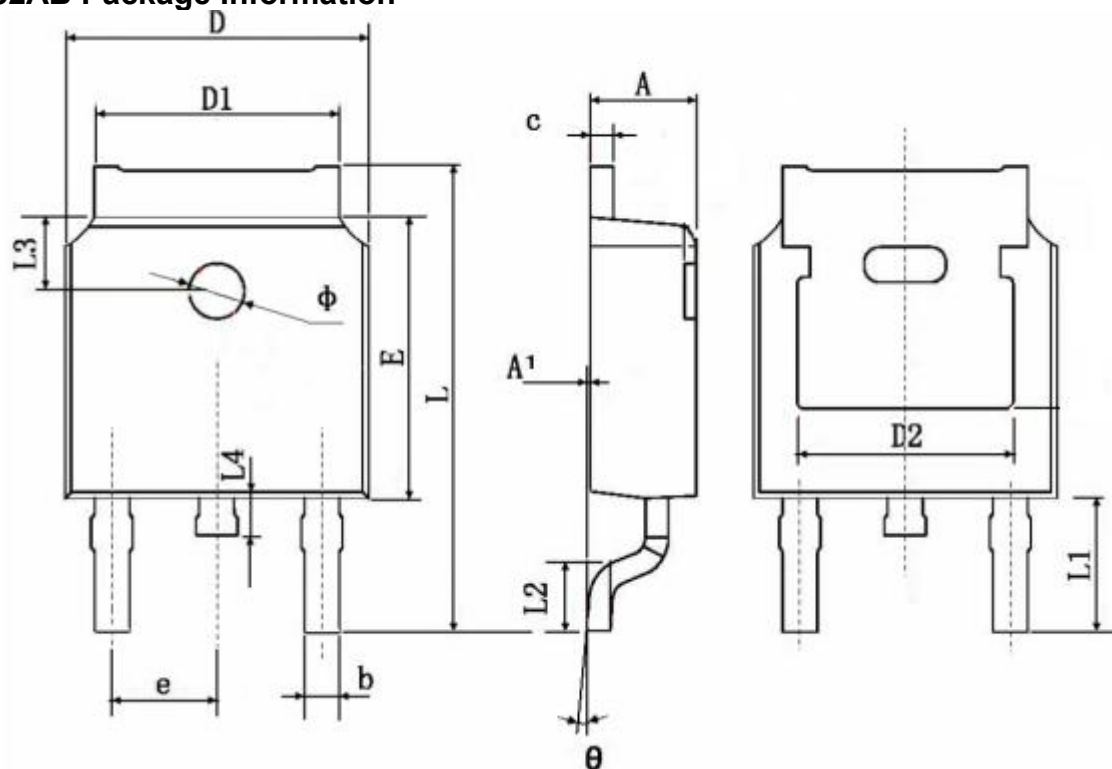


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.086	0.094
A1	0.000	0.130	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.500	0.201	0.217
D2	4.830 REF		0.190 REF	
E	6.000	6.200	0.236	0.244
e	2.190	2.390	0.086	0.094
L	9.800	10.500	0.386	0.413
L1	2.900 BSC		0.114 BSC	
L2	1.400	1.800	0.055	0.070
L3	1.600 REF		0.063 REF	
L4	0.600	1.000	0.023	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°